



European Library-based flow of Embedded Silicon Test Instruments

ELESIS final review
December 2015



Goal & Technology

Goal: Test Access Standardization of Embedded Test Instruments and protocol automation

Method: High-speed serial test interface with LVDS and serialization

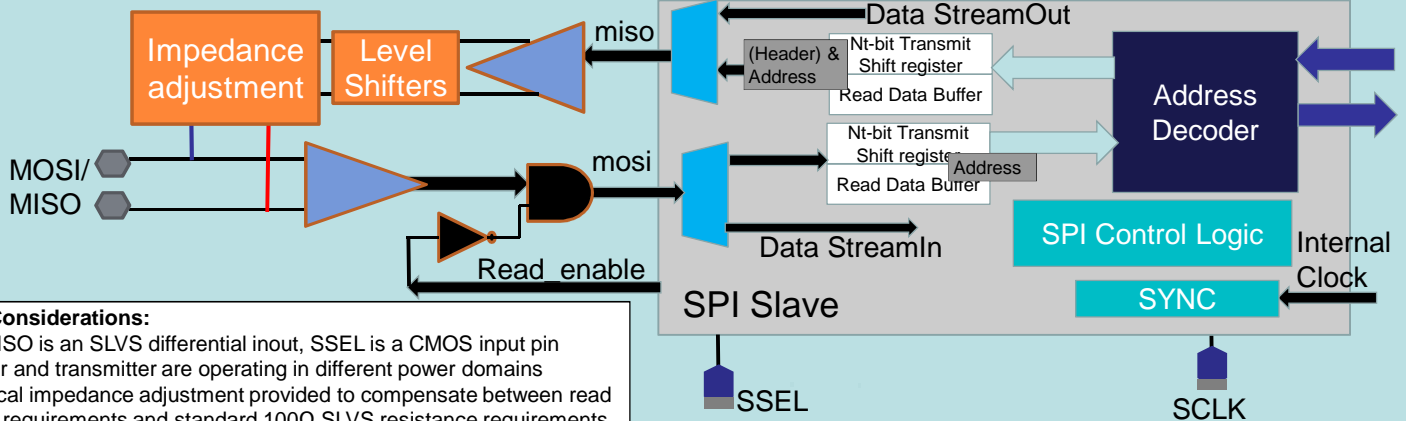
New test architecture for streaming and distributing test data with high bandwidth and low pin count

Test Access Standardization of ETI: High-Speed Link

ELESIS KPI's

Key benefits	ELESIS KPI
Test Interface Standardization	QUALITY
Test development protocol automation	TIME
Test Pin reduction	COST

SPI Extension to enable higher operating frequencies



Design Considerations:

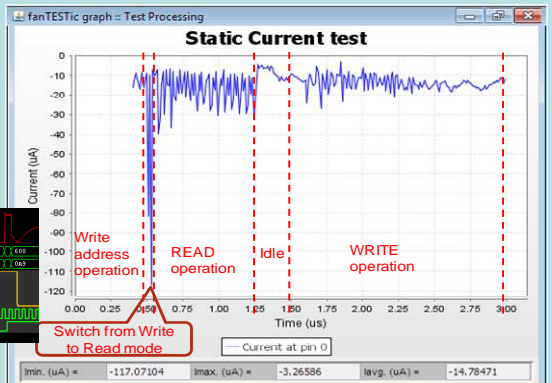
- MOSI/MISO is an SLVS differential inout, SSEL is a CMOS input pin
- Receiver and transmitter are operating in different power domains
- Dynamic impedance adjustment provided to compensate between read and write requirements and standard 100Ω SLVS resistance requirements

ELESIS technology results: Crucial Design Achievements, Test Protocol Automation

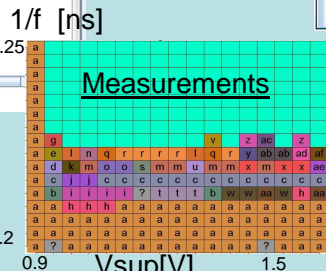
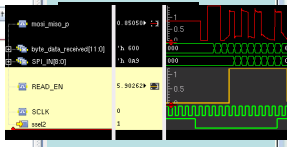
Automatic Test Protocol Generation with D4T Systems fanTESTic tool

The screenshots show the fanTESTic tool interface. The top part displays the 'Test protocol description for SPI Master' with various test phases and parameters. The bottom part shows the 'STIL Protocol Generation' window, which outputs a STIL file for the testbench.

Analysis: Current and Power Measurement



Simulation Testbench Generation



High Speed test link - final achievements:
 Max Speed <= 300 MHz
 Pincount <= 3
 Power (static) = 16.8μW
 Power(dynamic) = 17.736μW
 Area = 17600 μm²
 BER < 1x10⁻¹² @300MHz